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FOR IMMEDIATE RELEASE

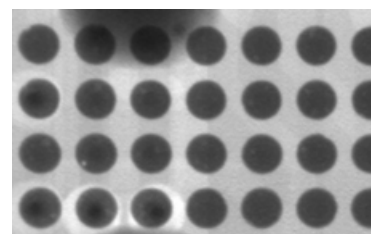
Press Release

YINCAE's Fully Flux Residue Compatible Underfill: UF 158HA

(Albany, NY) 08/15/2022 — YINCAE is excited to announce that we have developed UF 158HA that is fully compatible with flux residue and high performance underfill. Using UF 158HA can eliminate the cleaning process and pollution from the cleaning process, and simplify the manufacturing process.

Due to its unique properties, UF 158HA is not only a high performance underfill but also can function as a solder mask with eliminating electric migration. **The benefits of using UF 158HA are:**

- ❖ Fully compatible with all no-clean solder paste flux residue
- ❖ Eliminating cleaning process and its pollution
- ❖ Large cost saving
- ❖ Pass 5x260 °C without any deformation of solder joint
- ❖ Better than all competitors' underfill with cleaning process
- ❖ Be able to flow into 20μ gap
- ❖ Withstands high temperature up to 400 °C.
Reflow



UF 158HA after 5x260°C

This material can be used for BGA, flip chip, wafer-level chip scale package applications. It is also suitable for bare chip protection in a variety of advanced packages such as memory cards, chip carriers, hybrid circuits and multi-chip modules. It is designed for high production and friendly environments where process speed, mechanical shock and reliability are key concerns.

For more information on YINCAE's UF 158HA or to learn more about what YINCAE offers, please email us at: info@yincae.com. You can also find more information by visiting our website at: www.yincae.com

Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of thermal interface materials, underfill solutions, die attach adhesives, electronic materials, & high-performance coatings used in microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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